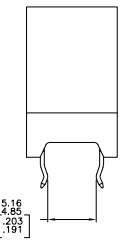
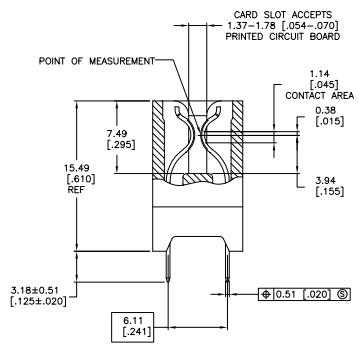
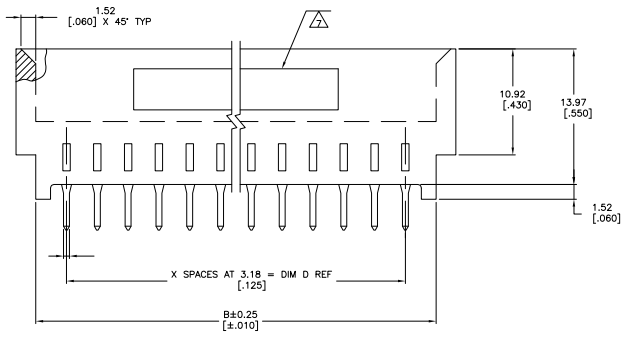
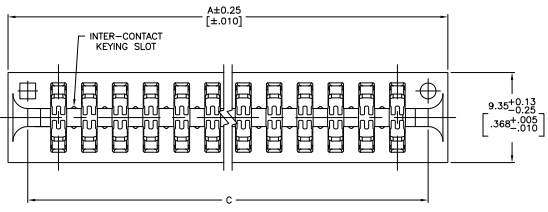


- △ HOUSING: GLASS FILLED POLYESTER; COLOR: BLACK.
- △ CONTACT: PHOSPHOR BRONZE.
- △ NICKEL UNDERPLATE: 0.00127 [.000050] MIN - ALL OVER.
- △ TIN-LEAD PLATE: 0.00254 [.000100] MIN - SOLDER POSTS.
- △ GOLD PLATE: 0.00076 [.000030] MIN - CONTACT AREA.
- △ NICKEL PLATE PER MIL-G-45204.
- △ GOLD PLATE PER QQ-N-290.
- △ AMP PART NUMBER AND DATE CODE ARE MARKED IN APPROXIMATE AREA SHOWN, EITHER SIDE.
- 8. RECOMMENDED PCB FINISHED HOLE DIA: 1.02 ± 0.08 [.040 ± .003].
- 9. THE RETENTIVE FEATURE OF THIS CONNECTOR IS DESIGNED FOR FULL SEATING IN .052 ± .008 THICK CIRCUIT BOARDS. FOR APPLICATIONS IN BOARDS OF OTHER THICKNESSES CONTACT AMP INCORPORATED.
- △ MATTE TIN PLATE: 0.00254 [.000100] MIN - SOLDER POSTS.



BOARD RETENTION FEATURE

3-10	15.88 [.625]	22.22 [.875]	22.22 [.875]	26.29 [1.035]	5	6	△	5-650207-1
3-10	15.88 [.625]	22.22 [.875]	22.22 [.875]	26.29 [1.035]	5	6		650207-1
BOARD RETENTION LOCATION	D	C	B	A	X	NO OF POSN.	PART NUMBER	

THIS DRAWING IS A CONTROLLED DOCUMENT. SEE SUBKEY/DATE 1/10/01

INCHES	3.18	108-9039	3.18	108-9039
MILLIMETERS	125	108-9039	125	108-9039
DATE	10/07/99	108-9039	10/07/99	108-9039
REV	A	108-9039	A	108-9039
REV	1	108-9039	1	108-9039
REV	2	108-9039	2	108-9039
REV	3	108-9039	3	108-9039
REV	4	108-9039	4	108-9039
REV	5	108-9039	5	108-9039
REV	6	108-9039	6	108-9039
REV	7	108-9039	7	108-9039
REV	8	108-9039	8	108-9039
REV	9	108-9039	9	108-9039
REV	10	108-9039	10	108-9039

CONNECTOR ASSEMBLY, STANDARD EDGE II, .052 ± .008 THICK BOARD RETENTION

DATE: 10/07/99

REV: A

REV: 1

REV: 2

REV: 3

REV: 4

REV: 5

REV: 6

REV: 7

REV: 8

REV: 9

REV: 10